



Material Content Data Sheet



Sales Product Name		IPL65R195C7		Issued		24. January 2018		
MA#		MA001038958						
Package		PG-VSON-4-1		Weight*		188.04 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.186	2.23	2.23	22259	22259
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		68	
	non noble metal	zinc	7440-66-6	0.051	0.03		270	
	non noble metal	iron	7439-89-6	1.017	0.54		5409	
wire	non noble metal	copper	7440-50-8	41.300	21.96	22.54	219633	225380
	non noble metal	copper	7440-50-8	0.957	0.51	0.51	5091	5091
	encapsulation	organic material	carbon black	1333-86-4	0.218	0.12		1162
plastics	plastics	epoxy resin	-	11.250	5.98		59829	
	inorganic material	silicondioxide	60676-86-0	97.758	51.98	58.08	519872	580863
leadfinish	non noble metal	tin	7440-31-5	2.397	1.27	1.27	12750	12750
plating	noble metal	silver	7440-22-4	0.252	0.13	0.13	1340	1340
solder	noble metal	silver	7440-22-4	0.090	0.05		477	
	non noble metal	tin	7440-31-5	0.072	0.04		381	
	non noble metal	lead	7439-92-1	3.424	1.82	1.91	18209	19067
heatspreader	inorganic material	phosphorus	7723-14-0	0.008	0.00		40	
	non noble metal	zinc	7440-66-6	0.030	0.02		160	
	non noble metal	iron	7439-89-6	0.601	0.32		3198	
	non noble metal	copper	7440-50-8	24.418	12.99	13.33	129852	133250
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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